

136	1	((US-5863814-\$ r US-5956606-\$ or US-6000603-\$ or US-5968670-\$ r US-5786635-\$ or US-5573859-\$ or US-5880017-\$ r US-5388327-\$ or US-5591941-\$ or US-6465747-\$ or US-6286206-\$ r US-6158644-\$ or US-6283359-\$ or US-6472611-\$ or US-6458623-\$ or US-5535526-\$ or US-6495441-\$ or US-6333554-\$ or US-6344690-\$ or US-5885849-\$ or US-5801446-\$ or US-5937514-\$ or US-6162661-\$ or US-6324754-\$ or US-6354485-\$ or US-5534127-\$).did. or (US-6075289-\$ or US-5801441-\$ or US-5518964-\$ or US-6194291-\$ or US-6104087-\$ or US-6184062-\$ or US-5931371-\$ or US-6326241-\$ or US-6303408-\$ or US-6373717-\$ or US-6271107-\$ or US-6281106-\$ or US-6255136-\$ or US-6245186-\$ or US-6268662-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20020157247-\$ or US-20020029902-\$ or US-20020047216-\$ or US-20020033525-\$ or US-20020100972-\$ or US-20010015495-\$ or US-20020151164-\$ or US-20020085364-\$ or US-20020046856-\$ or US-20020068453-\$ or US-20020041036-\$ or US-20010048591-\$ or US-20010030882-\$ or US-20010020636-\$).did.) and (spherical near core).ti,ab,clm.) and (pad).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 09:26
-	2816	standoff.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:37
-	12	standoff.ti,ab,clm. and (melting near temperature).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:39
-	50	standoff and (melting near temperature) and spherical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:41
-	40	(standoff and (melting near temperature) and spherical) and (solder or soldering or soldered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:43

-	11	((stand ff and (m lting near temp rature) and sph rical) and (solder r soldering r sold red)) and (stand ff same spherical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:44
-	1	((standoff and (melting near temp rature) and spherical) and (solder or soldering or soldered)) and (standoff near5 spherical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:44
-	40	((standoff and (melting near temperature) and spherical) and (solder or soldering or soldered)) and (standoff near20spherical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:44
-	3	((standoff and (melting near temperature) and spherical) and (solder or soldering or soldered)) and (standoff near20 spherical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:45
-	5	(standoff near20 spherical).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:45
-	13	((standoff or stand-off or (stand near off) near20 spherical).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:47
-	55	((standoff or stand-off or (stand near off) near20 spherical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:47
-	5	((standoff or stand-off or (stand near off) near20 spherical)) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:49
-	0	(spherical near core) and (attachment near layer) and jig	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:51
-	0	(spherical near core) and (attachment near layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:51

-	1429	sph ical near cor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:52
-	3	(spherical n ar core) and jig and flux	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:52
-	5	(spherical near core) and standoff	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:52
-	8	(US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.	USPAT; US-PGPUB	2003/01/03 10:54
-	3	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and eutectic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:55
-	6	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and (attach or attachment or attached or attaching)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:55
-	4	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and (attach or attachment or attached or attaching).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:56
-	8	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and ((melt or melting or melted) near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:57
-	5	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and ((melt r m lting or m lted) n ar temp ratur).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:58

-	3	((US-6184062-\$ r US-5931371-\$ r US-6303408-\$ r US-6208025-\$ r US-6002168-\$).did. r (US-20010015495-\$ or US-20020041036-\$ r US-20010048591-\$).did.) and (standoff r stand-off r "stand ff").ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 10:59
-	8	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and (standoff or stand-off or "stand off")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:00
-	5	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and (standoff or stand-off or "stand off")) and (aluminum or bronze or polymer or copper).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:03
-	0	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and (solder near flux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:04
-	0	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and (flux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:04
-	3	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and pad) and die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:06
-	3	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and pad) and die) and board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:06
-	8	((US-6184062-\$ or US-5931371-\$ or US-6303408-\$ or US-6208025-\$ or US-6002168-\$).did. or (US-20010015495-\$ or US-20020041036-\$ or US-20010048591-\$).did.) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:07
-	4872	solder near flux	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:07

-	289	(s ld r n ar flux) and spherical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:08
-	208	((solder near flux) and spherical) and board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:08
-	61	((solder near flux) and spherical) and board and die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:10
-	10	((solder near flux) and spherical) and board) and die) and jig	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:08
-	6	((solder near flux) and spherical) and board) and die) and standoff	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:10
-	0	(spherical near core) and standoff and (flux)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:11
-	5	(spherical near core) and standoff	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:11
-	50	standoff and spherical and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:12
-	12	standoff and spherical and (melting near temperature).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:13
-	17450	(standoff or stand-off or (stand near off))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:14

-	594	(standoff r stand-off r (stand near ff)) near member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:17
-	7	((stand ff r stand-off or (stand near off)) near member) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:16
-	81	(standoff or stand-off or (stand near off)) and (melting near temperature).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:18
-	28	((standoff or stand-off or (stand near off)) and (melting near temperature).ti,ab,clm.) and composite	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:18
-	10	((standoff or stand-off or (stand near off)) and (melting near temperature).ti,ab,clm.) and composite) and die and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:20
-	62	(standoff or stand-off or (stand near off)) near5 (sphere or spherical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:20
-	6	((standoff or stand-off or (stand near off)) near5 (sphere or spherical)) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:21
-	1	((standoff or stand-off or (stand near off)) near5 (sphere or spherical)) and (melting near temperature)) and flux	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:21
-	18	(standoff or stand-off or (stand near off)) and (sphere or spherical) and die and pad and (bond or bonding or bonded) and flux and (solder or soldered or soldering) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:28
-	324576	composite.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:28

-	3974	comp sit .ti,ab,clm. and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:29
-	312	(composit .ti,ab,clm. and sold r) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:30
-	97	(composite.ti,ab,clm. and solder) and (melting near temperature).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:30
-	6	((composite.ti,ab,clm. and solder) and (melting near temperature).ti,ab,clm.) and (sphere or spherical or spherically).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:33
-	55	die and pad and (sphere or spherical or spherically) and board and (melting near point).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:36
-	2	(die and pad and (sphere or spherical or spherically) and board and (melting near point).ti,ab,clm.) and (spherical near core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:37
-	790	(spherical near core).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:38
-	4	((spherical near core).ti,ab,clm.) and (melting near temperature).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:39
-	5639	(standoff or stand-off or (stand near off)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:40
-	17	((standoff or stand-off or (stand near off)).ti,ab,clm.) and (melting near temperature).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:41

-	230	((standoff or stand-ff r (stand near off)) sam (sphere r spherical r spherically))	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:42
-	19	((stand ff r stand-off or (stand n ar ff)) same (sphere or spherical or spherically))) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:44
-	6	((standoff or stand-off or (stand near off)) same (sphere or spherical or spherically))) and (melting near temperature)) and composite	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 11:46
-	54	board and contact and substrate and package and (sphere or spherical or spherically) and (melting near temperature) and composite and eutectic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 12:00
-	12	(board and contact and substrate and package and (sphere or spherical or spherically) and (melting near temperature) and composite and eutectic) and (standoff or stand-off or (stand near off))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:12
-	0	edward and martin and tod and biggs	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:12
-	688	intel and edward and martin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:13
-	92	(intel and edward and martin) and composite	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:13
-	52	((intel and edward and martin) and composite) and board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:14
-	3	((intel and edward and martin) and composite) and board) and spherical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:14

-	14	((print d n ar circuit n ar b ard) or pcb) sam (packag r packaging) same substrate same (attach or attaching r attach d) sam comp site)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:20
-	0	((((print d n ar circuit n ar b ard) r pcb) same (package or packaging) same substrate same (attach or attaching or attached) same composite)) and (spherical near core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:18
-	2	((((printed near circuit near board) or pcb) same (package or packaging) same substrate same (attach or attaching or attached) same composite)) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:19
-	1	((((printed near circuit near board) or pcb) same (package or packaging) same substrate same (attach or attaching or attached) same composite)) and (standoff or stand-off or (stand near off))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:20
-	1548	((printed near circuit near board) or pcb) and (package or packaging) and substrate and (attach or attaching or attached) and composite)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:22
-	169	((((printed near circuit near board) or pcb) and (package or packaging) and substrate and (attach or attaching or attached) and composite)) and (melting near temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:23
-	5	((((printed near circuit near board) or pcb) and (package or packaging) and substrate and (attach or attaching or attached) and composite)) and (melting near temperature)) and (spherical near core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:25
-	236	(spherical near core).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:25
-	3	((spherical near core).clm.) and (melting near temperature).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:34
-	55	(spherical near core) and (melting near (point or temperature)) and composite	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:38

-	21	((spherical near core) and (melting near (point right mp rature)) and (chip site) and (die chip rs mic nduct r)	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2003/01/03 14:39
-	8754	composit n ar5 c ntact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:40
-	4090	(composite near5 contact).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:41
-	18	((composite near5 contact) same (sphere or spherical)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:52
-	4	((composite near5 contact) same (sphere or spherical)) and (semiconductor or die or chip or ic) and (solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:53
-	89	((composite near5 contact) and (sphere or spherical)) and (semiconductor or die or chip or ic) and (solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:55
-	76	((((composite near5 contact) and (sphere or spherical)) and (semiconductor or die or chip or ic) and (solder)) and (package or packaging) and (board or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:56
-	43	(((((composite near5 contact) and (sphere or spherical)) and (semiconductor or die or chip or ic) and (solder)) and (package or packaging) and (board or pcb) and (melt or melting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:57
-	35	((((((composite near5 contact) and (sphere or spherical)) and (semiconductor or die or chip or ic) and (solder)) and (package or packaging) and (board or pcb) and (melt or melting)) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:57
-	11	((((((((composite near5 contact) and (sphere or spherical)) and (semiconductor or die or chip or ic) and (solder)) and (package r packaging) and (board r pcb) and (melt or m lting)) and pad) and (sph re or spherical or sph rically or ball).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 14:58

-	5	((((((composite n ar5 c ntact) and (spher or sph rical)) and (semic nductor or di r chip r ic) and (s ld r)) and (packag r packaging) and (b ard r pcb)) and (melt r melting)) and pad) and (spher or spherical r spherically r ball).ti,ab,clm.) and (melt r melting or melted).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:01
-	27983	((melting) near (point or temperature)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:02
-	99970	(spherical or spherically or sphere or ball).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:03
-	1178	((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:04
-	124	((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).clm.) and (pcb or board).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:05
-	8	((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).clm.) and (pcb or board).ti,ab,clm.) and (composite.ti,ab,clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:05
-	1279	((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:04
-	321	((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).ti,ab,clm.) and (composite)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:05
-	33	((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).ti,ab,clm.) and (composite)) and (pcb or board).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:05
-	73	((melting) near (point or t mp ratur)).clm.) and (spherical or sph rically or sphere r ball).ti,ab,clm.) and (comp sit)) and (pcb or board)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:05

-	33	((((((m lting) n ar (p int r t mp ratur))).clm.) and (spherical or spherically r sph r r ball).ti,ab,clm.) and (c mposit)) and (pcb r b ard)) and c re	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:05
-	22	((((((melting) n ar (point or temperature)).clm.) and (spherical or spherically or sphere or ball).ti,ab,clm.) and (composite)) and (pcb or board)) and core) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:06
-	22	((((((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).ti,ab,clm.) and (composite)) and (pcb or board)) and core) and pad) and (die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:10
-	9	((((((((melting) near (point or temperature)).clm.) and (spherical or spherically or sphere or ball).ti,ab,clm.) and (composite)) and (pcb or board)) and core) and pad) and (die or chip or ic)) and ((sphere or spherical) near5 core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:15
-	321	substrate same (collapse or collapsed or collapsing) same (pcb or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:16
-	1750	(substrate same (collapse or collapsed or collapsing) same (pcb or board)) (spherical near core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:18
-	0	(substrate same (collapse or collapsed or collapsing) same (pcb or board)) and (spherical near core)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:18
-	1429	spherical near core	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:18
-	40	(spherical near core) and (collapse or collapsing or collapsed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:18
-	20	((spherical near core) and (collapse or collapsing or collapsed)) and (m lt or m lting r melted)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:20

-	3	((spherical near core) and (collapse or collapsing or collapse)) and (semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:20
-	3	(collapsing) and (spherical near core) and (semiconductor or chip or die or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:21
-	22	(spherical near core) near20 (melt or melting or melted)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:27
-	58	(spherical near core) same (melt or melting or melted)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:27
-	12	((spherical near core) same (melt or melting or melted)) and (pcb or board) and (solder) and (chip or die or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/03 15:29